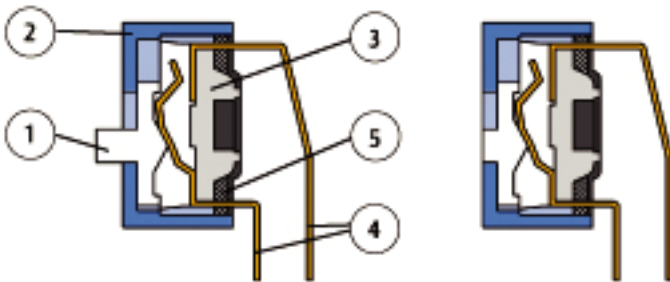
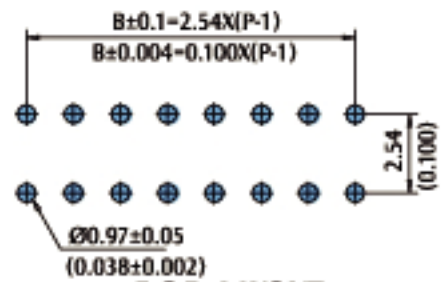
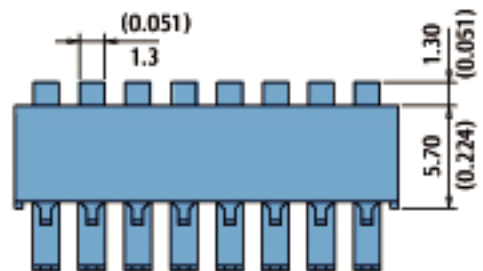


RA CONSTRUCTION

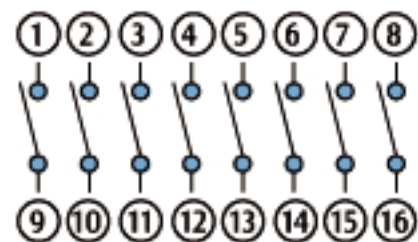


1. Terminal plating by gold gives excellent results when soldering.
2. RA series (raised actuator)
3. Low contact resistance, and self-clean on contact area.
4. Double contacts offer high reliability.
5. All materials are UL94V-0 grade fire retardant plastics.

ITEM	Description	Materials	Treatment
1	Actuator	UL94V-0 PBT	White
2	Cover	UL94V-0 PBT	Blue, Red, Black
3	Base	UL94V-0 PBT	Black
4	Terminal Contact	Phosphor bronze	Gold Plating
5	Potting	Epoxy	Black

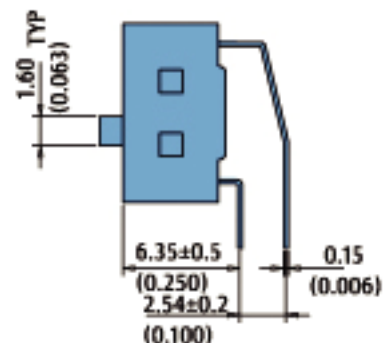


P.C.B. LAYOUT



CIRCUIT DIAGRAM

TERMINAL TYPE



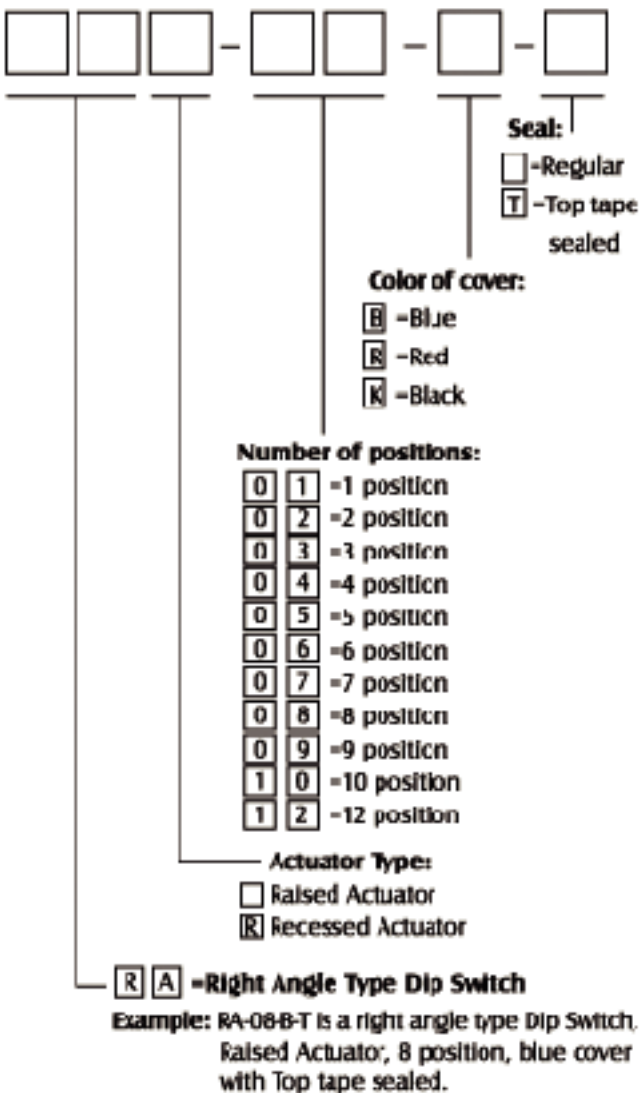
RA SERIES

Dip Switch RA Series

MODEL

PART NO.	NO. OF POS	DIM A	
RA-01	01	3.84	0.151
RA-02	02	6.08	0.239
RA-03	03	8.92	0.351
RA-04	04	11.16	0.439
RA-05	05	13.70	0.539
RA-06	06	16.24	0.539
RA-07	07	19.08	0.751
RA-08	08	21.32	0.839
RA-09	09	24.16	0.951
RA-10	10	26.40	1.039
RA-12	12	31.48	1.239

HOW TO ORDER



PACKING

All DIP switches are shipped in standard IC tubes with all poles in "OFF" position.

SPECIFICATION

ELECTRICAL

Electrical life: 2000 operation cycles per switch 24VDC, 25mA.

Non-Switching Rating: 100mA, 50 VDC

Switching Rating: 25mA, 24VDC.

Contact resistance: (a) 50mΩ max. at Initial

(b) 100mΩ max. after life test.

Insulation resistance: 100MΩ min. (at 500VDC)

Dielectric Strength: 500VAC/1 minute.

Capacitance: 5pF max.

Circuit: Single pole single throw

MECHANICAL

Mechanical life: 2000 operations per cycle switch

Operation Force: 800gf max.

Stroke: 2.0mm

Operation Temp: -25° C to +70° C

Storage Temp: -40° C to +85° C

Vibration Test: MIL-STD-202F METHOD 201A

Frequency: 10-55-10Hz/1 min

Directions: X, Y, Z, three mutually perpendicular directions.

Time: 2 hours each direction.

High reliability.

Shock Test: MIL-STD-202F METHOD 213B.

CONDITION A

GRANTY: 50G (peak value), 11 m/sec.

Direction and times: 6 sides and three times in each direction. High reliability.

SOLDERING AND CLEANING PROCESSES

For best results, please follow these recommendations:

Keep all switch contacts in their "OFF" position for all operations.

WAVE SOLDERING: Recommended solder temperature at 500 F (260° C) max. 5 seconds.

HAND SOLDERING: Use a soldering iron of 30 watts, controlled at 608 F(320° C) approximately 2 seconds while applying solder.

CLEANING PROCESS: flux clean using force rinse, high agitation or triple bath cleaning method. Freon TF or TE give excellent results. When vapor methods are used, do not subject the switch to solvents at temperatures above 125 F (51° C).